MOSFET – SiC Power, Single N-Channel, D2PAK-7L

650 V, 12 mΩ, 145 A

NVBG015N065SC1

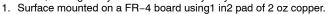
Features

- Typ. $R_{DS(on)} = 12 \text{ m}\Omega @ V_{GS} = 18 \text{ V}$ Typ. $R_{DS(on)} = 15 \text{ m}\Omega @ V_{GS} = 15 \text{ V}$
- Ultra Low Gate Charge ($Q_{G(tot)} = 283 \text{ nC}$)
- Low Effective Output Capacitance ($C_{oss} = 424 \text{ pF}$)
- 100% Avalanche Tested
- AEC-Q101 Qualified and PPAP Capable
- RoHS Compliant
- **Typical Applications**
- Automotive On Board Charger
- Automotive DC/DC Converter for EV/HEV
- Automotive Traction Inverter

MAXIMUM RATINGS (T_J = 25° C unless otherwise noted)

Para	Parameter				
Drain-to-Source Volta	V _{DSS}	650	V		
Gate-to-Source Voltag	je		V _{GS}	-8/+22	V
Recommended Operat ues of Gate – Source \		T _C < 175°C	V _{GSop}	-5/+18	V
Continuous Drain Current $R_{\theta JC}$ (Note 2)	Steady State	$T_{C} = 25^{\circ}C$	۱ _D	145	A
Power Dissipation $R_{\theta JC}$ (Note 2)			P _D	500	W
Continuous Drain Current $R_{\theta JA}$ (Notes 1, 2)	Steady State	T _C = 100°C	Ι _D	103	A
Power Dissipation $R_{\theta JA}$ (Notes 1, 2)			PD	250	W
Pulsed Drain Current (Note 3) $T_C = 25^{\circ}C$			I _{DM}	422	А
$ \begin{array}{c} \mbox{Single Pulse Surge} \\ \mbox{Drain Current Capability} \end{array} \begin{array}{c} T_A = 25^\circ C, \ t_p = 10 \ \mu s, \\ R_G = 4.7 \ \Omega \end{array} $			I _{DSC}	798	A
Operating Junction and Storage Temperature Range			T _J , T _{stg}	–55 to +175	°C
Source Current (Body Diode)			I _S	111	А
Single Pulse Drain-to-Source Avalanche Energy ($I_L = 13 A_{pk}, L = 1 \text{ mH}$) (Note 4)			E _{AS}	84	mJ
Maximum Lead Tempe from Case for 10 Seco		oldering, 1/8"	ΤL	245	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



 The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
Benetitive rating, limited by max junction temperature

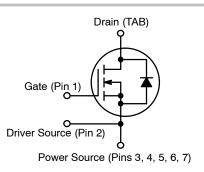
- 3. Repetitive rating, limited by max junction temperature. 4. E_{AS} of 84 mJ is based on starting $T_J = 25^{\circ}C$; L = 1 mH, $I_{AS} = 13$ A, $V_{DD} = 50$ V,
- V_{GS} = 18 V.



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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	18 m Ω @ 18 V	145 A

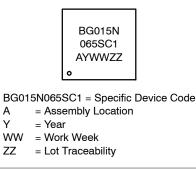


N-CHANNEL MOSFET



D2PAK-7L CASE 418BJ

MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

THERMAL CHARACTERISTICS

Parameter	Symbol	Мах	Units
Thermal Resistance Junction-to-Case (Note 2)	$R_{ extsf{ heta}JC}$	0.3	°C/W
Thermal Resistance Junction-to-Ambient (Notes 1, 2)	$R_{\theta JA}$	40	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS					•		
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0	V, I _D = 1 mA	650			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 20 mA	, refer to 25°C		0.12		V/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	$T_J = 25^{\circ}C$			10	μA
		V _{DS} = 650 V	T _J = 175°C			1	mA
Gate-to-Source Leakage Current	I _{GSS}	V _{GS} = +18/-	-5 V, V _{DS} = 0 V			250	nA
ON CHARACTERISTICS					•		
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS}	_S , I _D = 25 mA	1.8	2.8	4.3	V
Recommended Gate Voltage	V _{GOP}			-5		+18	V
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 15 V, I _D	= 75 A, T _J = 25°C		15		mΩ
		V_{GS} = 18 V, I_D	= 75 A, T _J = 25°C		12	18	
		V _{GS} = 18 V, I _D :	= 75 A, T _J = 175°C		16		
Forward Transconductance	9FS	V _{DS} = 10	V, I _D = 75 A		42		S
CHARGES, CAPACITANCES & GATE RES	SISTANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 325 V			4689		pF
Output Capacitance	C _{OSS}				424		
Reverse Transfer Capacitance	C _{RSS}				37		
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = -5/18 \text{ V}, \text{ V}_{DS} = 520 \text{ V},$ $I_D = 75 \text{ A}$			283		nC
Gate-to-Source Charge	Q _{GS}	I _D :	= 75 A		72		1
Gate-to-Drain Charge	Q _{GD}				64		
Gate-Resistance	R _G	f = 1 MHz			1.6		Ω
SWITCHING CHARACTERISTICS					1		1
Turn-On Delay Time	t _{d(ON)}	V _{GS} = -5/18	V, V _{DS} = 400 V,		23		ns
Rise Time	t _r		, R _G = 2.2 Ω, tive Load		26		
Turn-Off Delay Time	t _{d(OFF)}				49		
Fall Time	t _f				9.6		
Turn–On Switching Loss	E _{ON}				167		μJ
Turn–Off Switching Loss	E _{OFF}				276		
Total Switching Loss	E _{TOT}				443		
DRAIN-SOURCE DIODE CHARACTERIS				1			1
Continuous Drain-Source Diode Forward	I _{SD}	V _{GS} = -5	V, T _{.1} = 25°C			111	А

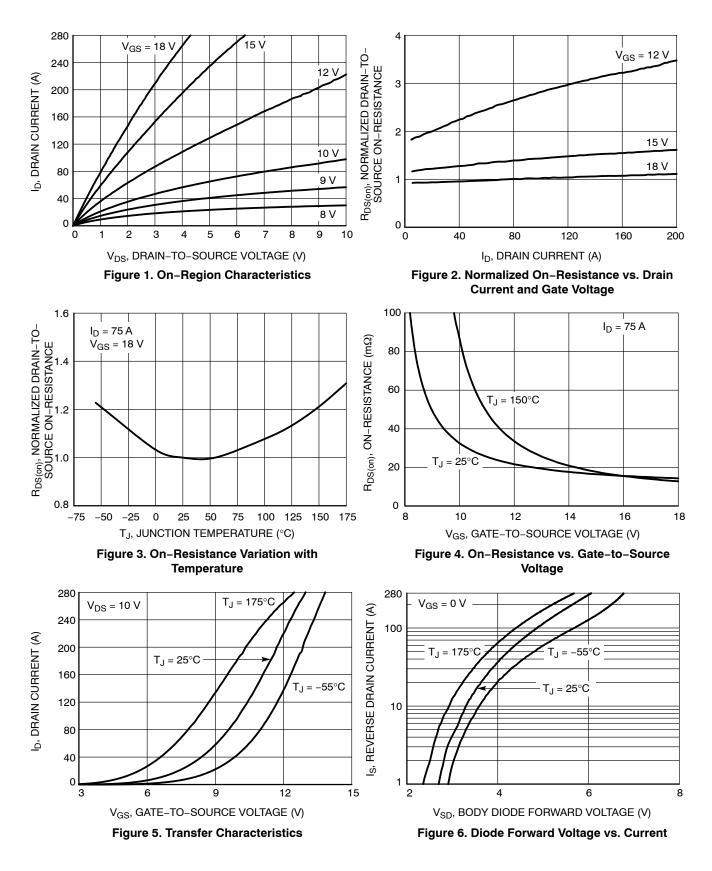
Continuous Drain–Source Diode Forward Current	I _{SD}	V_{GS} = -5 V, T_J = 25°C		111	A
Pulsed Drain-Source Diode Forward Current (Note 3)	I _{SDM}	V_{GS} = -5 V, T_J = 25°C		422	A
Forward Diode Voltage	V _{SD}	V_{GS} = –5 V, I_{SD} = 75 A, T_{J} = 25°C	4.8		V

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise stated)

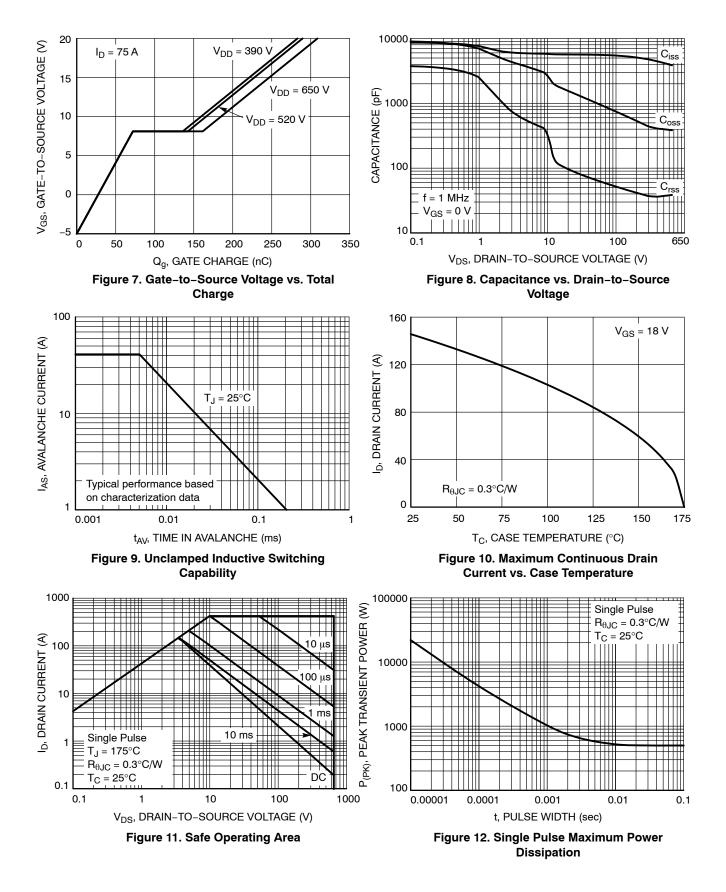
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit			
DRAIN-SOURCE DIODE CHARACTERISTICS									
Reverse Recovery Time	t _{RR}	V _{GS} = -5/18 V, I _{SD} = 75 A, dI _S /dt = 1000 A/μs		28		ns			
Reverse Recovery Charge	Q _{RR}	$dI_S/dt = 1000 A/\mu s$		234		nC			
Reverse Recovery Energy	E _{REC}			23		μJ			
Peak Reverse Recovery Current	I _{RRM}			16		А			
Charge time	Та			17		ns			
Discharge time	Tb]		11		ns			

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

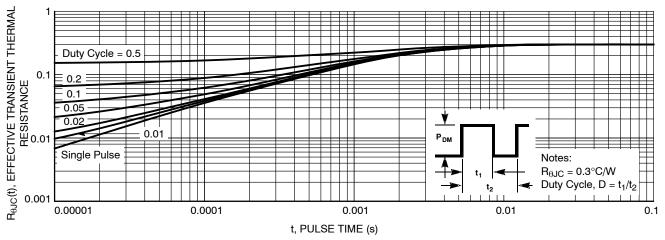


Figure 13. Junction-to-Case Transient Thermal Response Curve

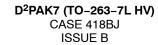
DEVICE ORDERING INFORMATION

Device	Package	${\sf Shipping}^{\dagger}$
NVBG015N065SC1	D2PAK-7L	800 / Tape & Reel

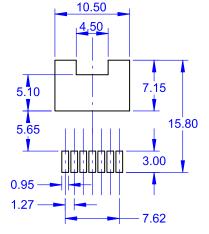
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DATE 16 AUG 2019

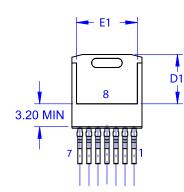




Α F L1 D b2 е h \oplus aaa B A M



LAND PATTERN RECOMMENDATION



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GENERIC **MARKING DIAGRAM***

XXXXXXXXX AYWWG
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XXXX = Specific Device Code А = Assembly Location Y = Year

- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

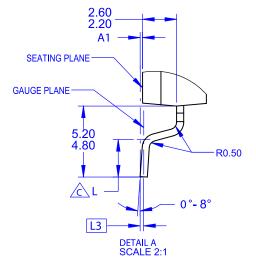
B	A
c2 —	
•	
H	
	A

NOTES:

A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION CB EXCEPT WHERE NOTED. B. ALL DIMENSIONS ARE IN MILLIMETERS.

C OUT OF JEDEC STANDARD VALUE. D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009. E. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

DIM	MILLIMETERS				
	MIN	NOM	MAX		
Α	4.30	4.50	4.70		
A1	0.00	0.10	0.20		
b2	0.60	0.70	0.80		
b	0.51	0.60	0.70		
С	0.40	0.50	0.60		
c2	1.20	1.30	1.40		
D	9.00	9.20	9.40		
D1	6.15	6.80	7.15		
E	9.70	9.90	10.20		
E1	7.15	7.65	8.15		
е	~	1.27	~		
Н	15.10	15.40	15.70		
L	2.44	2.64	2.84		
L1	1.00	1.20	1.40		
L3	~	0.25	~		
aaa	~	~	0.25		



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